

## ABSTRACT OF THE DISCLOSURE

A manufacturing method of a circuit substrate, in which an electronic circuit is formed on a surface of a base member by a solution jetting device. The manufacturing method comprises: jetting liquid drops of a solution which is supplied into a nozzle having a discharge port with an inner diameter of  $0.1\mu\text{m}$  to  $100\mu\text{m}$  and includes a plurality of fine particles to form an electronic circuit by melting and sticking to one another and a dispersant for dispersing the fine particles, from the discharge port toward the surface of the base member by applying a voltage of an arbitrary waveform to the solution to charge the solution; and exposing the jetted liquid drops received on the surface of the base member to light or heat to make the fine particles melt and stick to one another.